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**JUL 08 2004**

**YOR19960184 PATENT  
IBM-219**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : D.Y.Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2829  
For : **WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY,  
APPARATUS FOR USE THEREOF  
AND METHODS OF  
FABRICATION THEREOF**

Honorable Commissioner of Patents  
and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated April 8, 2004, please consider the following remarks with respect to the above-identified application as follows:

**REMARKS**

Applicants have amended the form of claims 8 and 32 to reflect proper dependency. The objection as to improper "antecedent basis" with respect to claims 36 and 49 has been corrected.

In answer to the Examiner's objection as to claim 60, said claim is merely claiming a plurality (i.e., more than one) of the structures defined in, for example, claim 1.

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